

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	62	YES
x	2	36	0.91	14	YES
□	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT

STACK-UP FOR REFERENCE

1.061 MM +/- 10%

LAYER 1 LT TOP ← 18 UM CU + 12.5 UM PLATING (30.5 UM)

CORE ← 1.0 MM CORE FR-4 LG 135 INCLUDING COPPER

LAYER 4 LT6 BOTTOM ← 18 UM CU + 12.5 UM PLATING (30.5 UM)

NOTES:

- PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TG 135 EPOXY LAMINATE WITH 18 UM COPPER PLATING AND 1 MM THICKNESS.
- ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE
- CIRCUIT PATHS ARE FOR REFERENCE ONLY.
- HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
- BOARD PLATED USING REFLOW OR SIMILAR METHOD.
- BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY. EQUIVALENT WET OR DRY FILM MAY BE USED.
- SILKSCREEN BOARD USING BLACK INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
- THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
 - * 2 COPPER LAYERS
 - * 1 MM BOARD THICKNESS
 - * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

Domino JTAG SPI

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Solder stop mask SOL (.STS) Rev. B